

DS55493,DS75493

DS55493 DS75493 Quad LED Segment Driver



Literature Number: SNOSBR6A

DS55493/DS75493 Quad LED Segment Driver

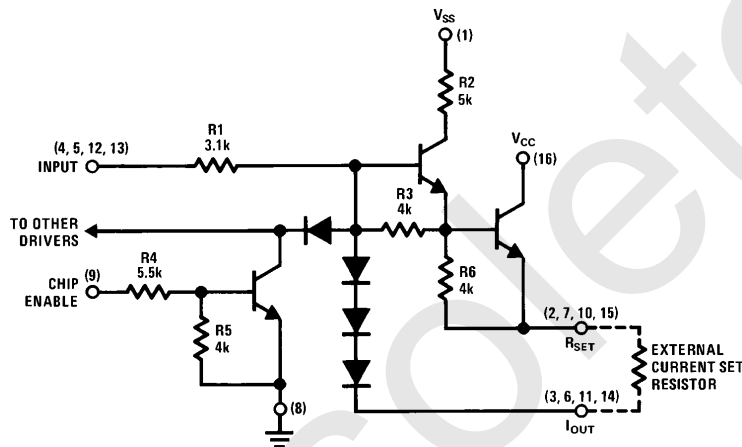
General Description

The DS55493/DS75493 is a quad LED segment driver. It is designed to interface between MOS IC's and LED's. An external resistor is required for each segment to drive the output current which is approximately equal to $0.7V/R_L$ and is relatively constant, independent of supply variations. Blanking can be achieved by taking the chip enable (CE) to a logical "1" level.

Features

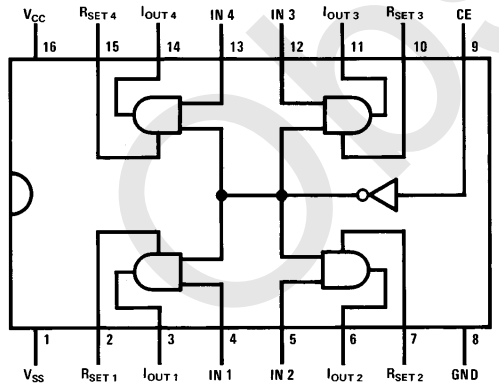
- Low voltage operation
- Low input current for MOS compatibility
- Low standby power
- Display blanking capability
- Output current regulation
- Quad high gain circuits

Schematic and Connection Diagrams



TL/F/7561-1

Dual-In-Line Package



Truth Table

CE	V _{IN}	I _{OUT}
0	1	ON
0	0	OFF
1	X	OFF

X = Don't care

TL/F/7561-2

Order Number DS55493J, DS75493J
or DS75493N
See NS Package Number J16A or N16A

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage	10V
Input Voltage	10V
Output Voltage	V_{CC}
Storage Temperature Range	-65°C to +150°C
Output Current (I_{OUT})	-25 mA
Maximum Power Dissipation* at 25°C	
Cavity Package	1371 mW
Molded Package	1280 mW
Lead Temperature (Soldering, 4 seconds)	260°C

*Derate cavity package 9.14 mW/°C above 25°C; derate molded package 10.24 mW/°C above 25°C.

Operating Conditions

	Min	Max	Units
Supply Voltage			
V_{CC}	3.2	8.8	V
V_{SS}	6.5	8.8	V
Temperature T_A			
DS75493	0	+70	°C
DS55493	-55	+125	°C

Electrical Characteristics ($V_{SS} \geq V_{CC}$) (Notes 2 and 3)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
I_{IN}	Input Current	$V_{SS} = \text{Max}, V_{IN} = 8.8V, V_{CC} = \text{Open}, V_{CE} = 0V$			3.2	mA	
		$I_{OUT} = R_{SET} @ 0V, V_{CE} = 8.8V$			3.6	mA	
I_{CE}	Chip Enable Input Current	$V_{CC} = \text{Max}, V_{SS} = \text{Max}, V_{CE} = 8.8V$, All Other Pins to GND			2.1	mA	
I_{OUT}	Output Current	$I_{OUT} @ 2.15V, R_L = 50\Omega$	$V_{CC} = \text{Min}, V_{SS} = 6.5V,$ $I_{CE} = 80 \mu A, V_{IN} = 6.5V$ Through 1.0 k Ω	-8	-13	mA	
			$V_{CE} = 0V, V_{IN} = 8.8V$		-16	-20	mA
I_{OL}	Output Leakage Current	$I_{OUT} = R_{SET} @ 0V$, Measure Current to Gnd, $V_{SS} = 8.8V$	$V_{CC} = \text{Min}, V_{CE} = 0V$ $V_{IN} = 8.8V$ Through 100 k Ω			-200	μA
			$V_{CE} = 6.5V$ Through 1.0 k $\Omega, V_{IN} = 8.8V$			-100	μA
I_{CC}	Supply Current, V_{CC}	$V_{CC} = \text{Max}, V_{SS} = \text{Max}$, All Other Pins to Gnd			40	μA	
I_{SS}	Supply Current	$V_{CC} = 0V$, All Other Pins to Gnd			40	μA	
		$V_{CC} = \text{Min}, V_{SS} = 8.8V$	$I_{OUT} @ 2.15V, V_{CE} = 8.8V$ Through 100 k Ω , $R_L = 50\Omega$	0.5	1.5	mA	
		$I_{OUT} = \text{Open}, R_{SET} = \text{Open},$ $V_{CE} = 0V$			1.4	mA	

Switching Characteristics $T_A = 25^\circ C$, nominal power supplies unless otherwise noted

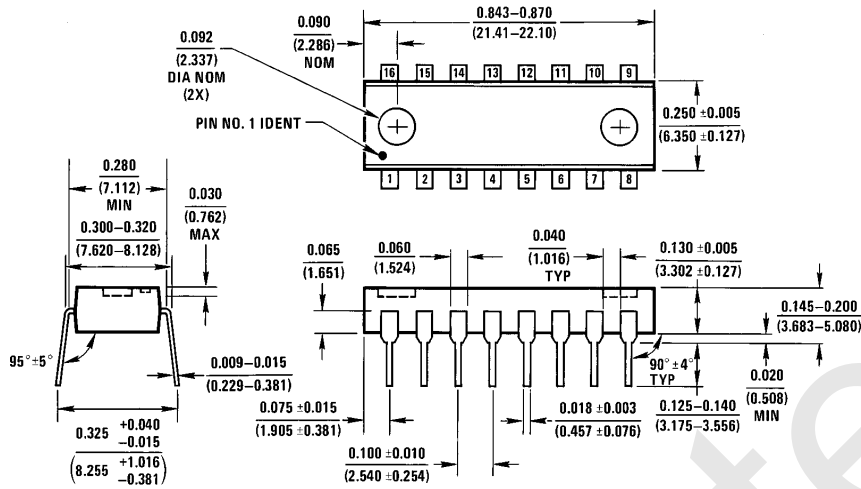
Symbol	Parameter	Conditions	Min	Typ	Max	Units
$t_{pd(OFF)}$	Propagation Delay to a Logical "0" From Input to Output	(See AC Test Circuit)		170	300	ns
$t_{pd(ON)}$	Propagation Delay to a Logical "1" From Input to Output	(See AC Test Circuit)		11	100	ns

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" provides conditions for actual device operation.

Note 2: Unless otherwise specified min/max limits apply across the 0°C to +70°C range for the DS75493 and across the -55°C to +125°C range for the DS55493.

Note 3: All currents into device pins shown as positive, out of device pins as negative, all voltages referenced to ground unless otherwise noted. All values shown as max or min on absolute value basis.

Physical Dimensions inches (millimeters) (Continued)



Order Number DS75493N
See NS Package Number N16A

N16A (REV E)

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